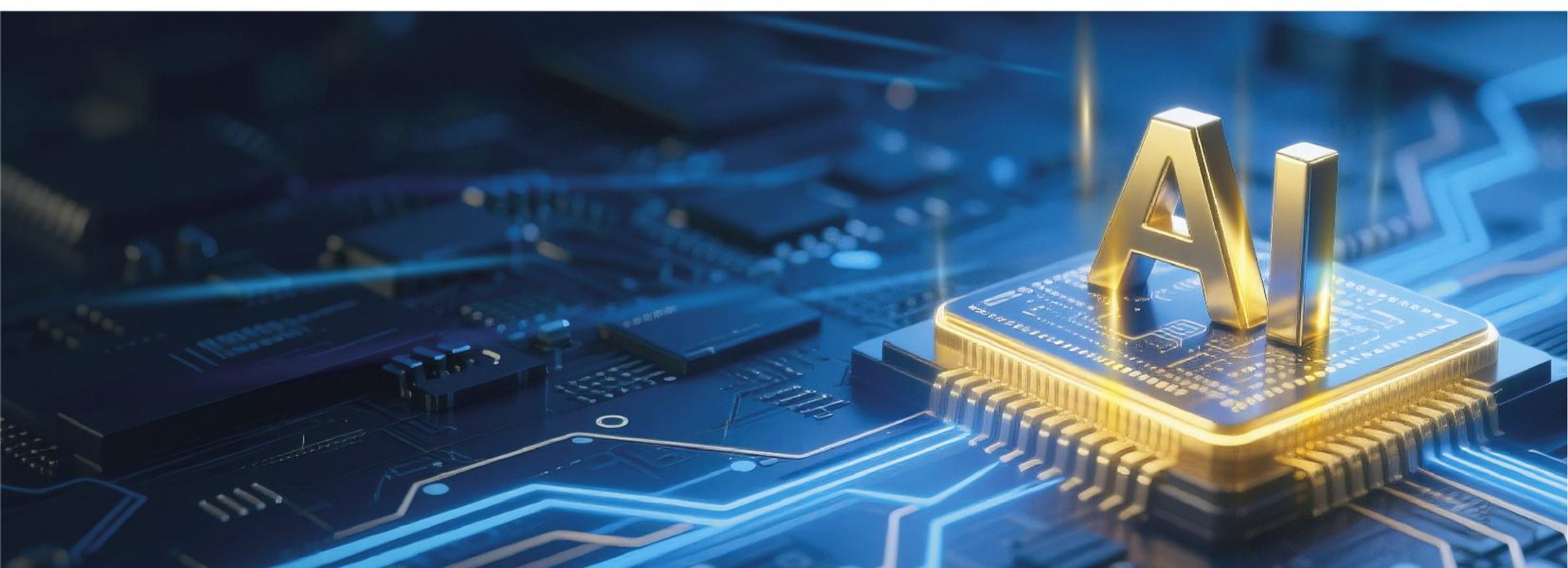


Provider of AI and High-End Storage Chip Solutions



Storage and Computing, Boundless,
QUANXING, Intelligently Connected



CONTENTS

01

Company Introduction

Company Profile \ Core Competencies \
Certifications & Awards \ Smart Manufacturing Base

02

AI Ultra-Memory Fusion Solution

Solution Overview \ Application Scenarios \
Solution Advantages \ Product Specifications

03

High-End Memory Chip Solutions

Solution Overview \ Enterprise Storage \ Industrial-Grade Storage \
Automotive-Grade Storage \ Embedded Storage \ Consumer-Grade Storage \
Industry-Specific Storage

04

Ecosystem Collaboration

Collaboration Models \ Contact Us

Company Introduction

BRAND POSITIONING

Provider of
AI and Premium Memory Chip Solutions

SLOGAN

Transcending Boundaries of Memory &
Computing Intelligent Connectivity by Quanxing

BRAND VISION

To Pioneer Dual Strategic Frontiers in
Artificial Intelligence and Premium Memory Chips

CORE VALUES

Technology Self-Reliance · Customer-Centricity
Scenario Deep-Dive · Ecosystem Co-Prosperity



30 Years
Industry Expertise



10000m²
Smart Manufacturing Base



Nationally Recognised
Specialised, Refined,
Distinctive and Innovative
"Little Giant" Enterprise



160
Intellectual Property
Achievements



3
National Standards
Developed



Provincial Research Centre
for High-Performance AI Chips
and Advanced Packaging

Shenzhen Quanxing Technology Co., Ltd. is an integrated provider of artificial intelligence and high-end storage chip solutions encompassing R&D, production, and sales. As a National High-Tech Enterprise and a National Specialized, Refined, Distinctive, and Innovative "Little Giant" enterprise, it operates across the dual strategic emerging tracks of artificial intelligence and high-end storage chips. Headquartered in Futian, the company operates a 10,000+ square meter smart manufacturing base—Shenzhen Quanxing Technology Co., Ltd.—and an international supply chain platform—HuiShi Asia. It owns the brands "QUANXING" and "KORX".

The company's core team has been deeply rooted in the industry for nearly 30 years, consistently prioritizing technological innovation. It operates a provincial-level High-Performance AI Chip and Advanced Packaging Engineering Technology Research Center, possessing full-stack capabilities spanning host controller design, chip R&D, packaging and testing, to module manufacturing. This enables the construction of a comprehensive high-end storage product line covering enterprise-grade, industrial-grade, automotive-grade, and consumer-grade applications. We have pioneered the AI Super Memory Fusion Solution, which transforms the universal capabilities of large AI models into specialized value for vertical scenarios across diverse industries at lower costs and energy consumption, accelerating the democratization of AI.

Currently, Quanxing Technology has accumulated over 160 intellectual property achievements in the fields of AI and storage chips, participated in the formulation of three national standards, obtained IATF 16949 international automotive quality system certification, and received honors including the AI Best Solution Award, AI Tianma High-Growth Enterprise, AI Storage Innovation Breakthrough Award, and Shenzhen Top 100 Brands. The company's business case has been included in the Tsinghua University China Business Case Center.

**AI Ultra-Memory
Fusion Solution**

**High-End Memory
Chip Solutions**



Core Technologies Under Independent Control

- Mastery of core technologies in AI and high-end storage chips
- Holds 160 intellectual property achievements
- Participation in the formulation of three national standards

Experienced Professional Team

- Core members hail from internationally renowned semiconductor enterprises
- Technical team boasts an average industry experience of nearly 30 years
- Established joint laboratories with multiple universities

Vertically integrated manufacturing capabilities

- Possesses 10,000m² smart manufacturing base
- Covering the entire process from main controller design, chip R&D, packaging testing to module manufacturing
- Digitalised management of production processes

Leveraging extensive industrial resources

- Establishing a comprehensive upstream-downstream industrial collaboration network
- Recognised as a National Specialised, Refined, Distinctive and Innovative "Little Giant" Enterprise
- Established Guangdong Provincial High-Performance AI Chip and Advanced Packaging Engineering Technology Research Centre

Core Competencies



Full-Stack Autonomous Controllable Production Capacity

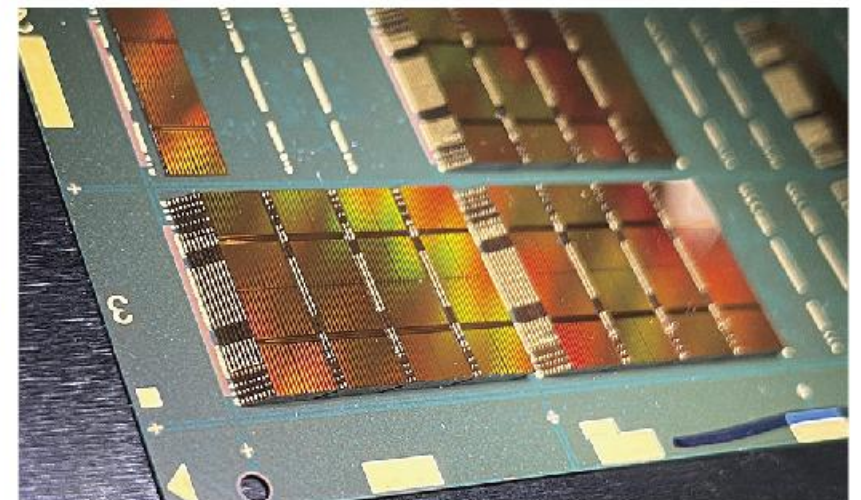
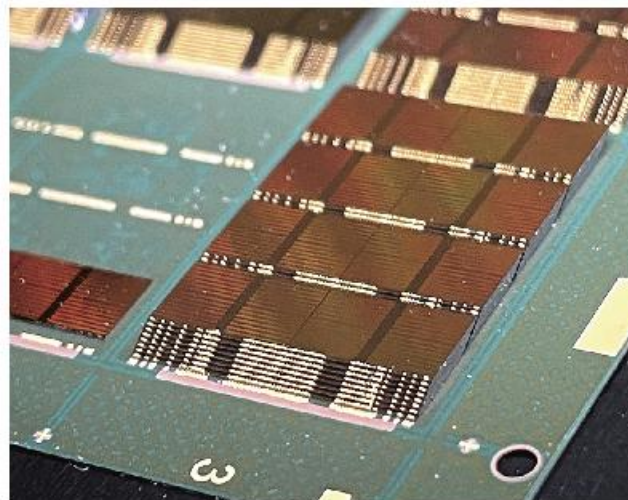
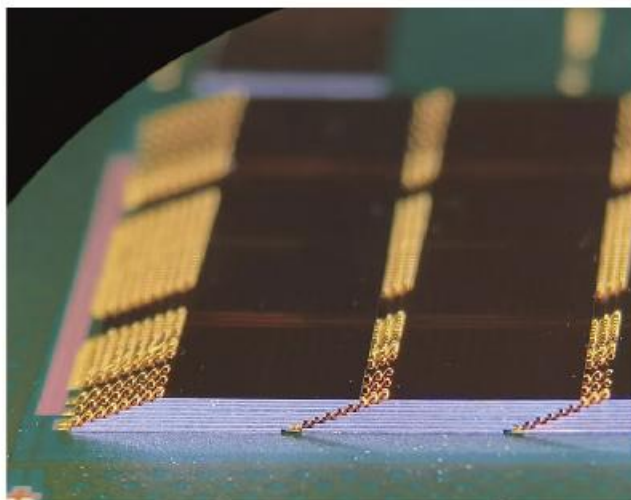
The subsidiary Quanta Smart Manufacturing Base boasts over 10,000 square metres of cleanroom facilities, equipped with advanced packaging and testing lines, module manufacturing lines, a technical R&D centre, and an engineering testing centre. This enables full autonomy and control across the entire process chain, from main controller design and chip development to packaging, testing, and module manufacturing. Through highly automated production and intelligent management, it achieves yield rates exceeding industry standards, meeting the stringent demands of manufacturing enterprise-grade, industrial-grade, automotive-grade, and consumer-grade storage products. This provides foundational support for next-generation high-performance storage solutions.



■ Packaging and Testing Production Line: Overcoming High-End Storage Packaging and Testing Bottlenecks

Offering one-stop services encompassing wafer packaging, testing, R&D design, and production, with mastery of advanced packaging technologies including SIP, BGA, LGA, and QFN. Possessing 16-die stacking chip mass production capability and reserves 32-die stacking technology, achieving a single flash memory chip capacity exceeding 2TB with industry-leading performance and reliability.

32-Die Stacking Process



■ Module Manufacturing Line: Benchmark for High-Precision Intelligent Manufacturing

Featuring four fully automated SMT production lines equipped with Panasonic NPM high-end placement equipment, alongside inline solder paste inspection, pre-reflow AOI inspection, and post-reflow AOI inspection. This enables 100% end-to-end monitoring to ensure every module meets production standards. Real-time production data monitoring via the MES system guarantees product traceability.



SMT

Technology R&D Centre: Breakthroughs in Domestic Storage Core Technologies

Establishing a high-end R&D laboratory equipped with advanced instruments including ultrasonic scanning (SAT), thermal shock chambers, constant temperature and humidity test chambers, torsion testing, and high-frequency vibration systems. These simulate extreme environmental conditions to validate product stability, durability, and wide-temperature adaptability, providing robust support for innovative product development and quality yield.

Laboratory



Engineering Test Centre: Full-chain Quality Assurance

In-house developed DRAM/NAND Flash testing software and algorithms establish a comprehensive verification system spanning wafer → chip → module. Through ageing tests, signal integrity analysis, and precise bad block screening, we ensure product longevity and data security meet factory standards.



Quality Management System: Rigorous Standards, Global Certification

Strict adherence to international standards including ISO 9001/14001 and IATF 16949 underpins a zero-defect management system spanning raw materials to finished products. This has secured supply chain certification from leading clients, enabling us to deliver premium storage solutions meeting high-performance requirements across all scenarios for global markets.

Reliability & Failure Analysis Technology	Quality Management System / Environmental Management System Certification
Reliability Testing Equipment and Capabilities	Tier 2 Material Management Evaluation Mechanism
Process Inspection Equipment and Capabilities	Process Capability Control
Process Environment Monitoring Equipment	Continuous Quality Improvement
RMA Customer Complaint Handling Process	Measurement System Analysis

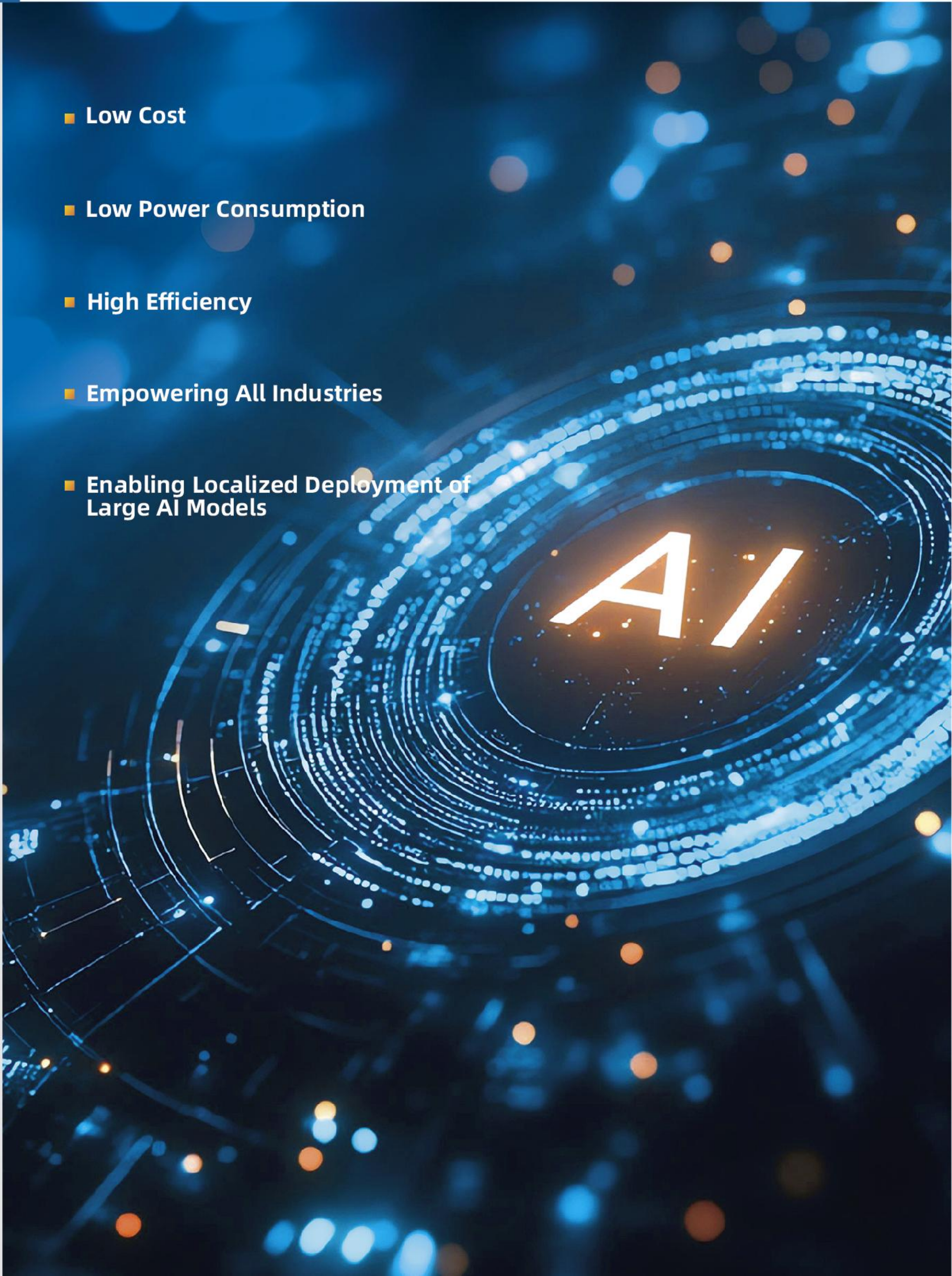


Automotive Grade IATF16949
Quality Management System Certification



AI Ultra-Memory Fusion Solution

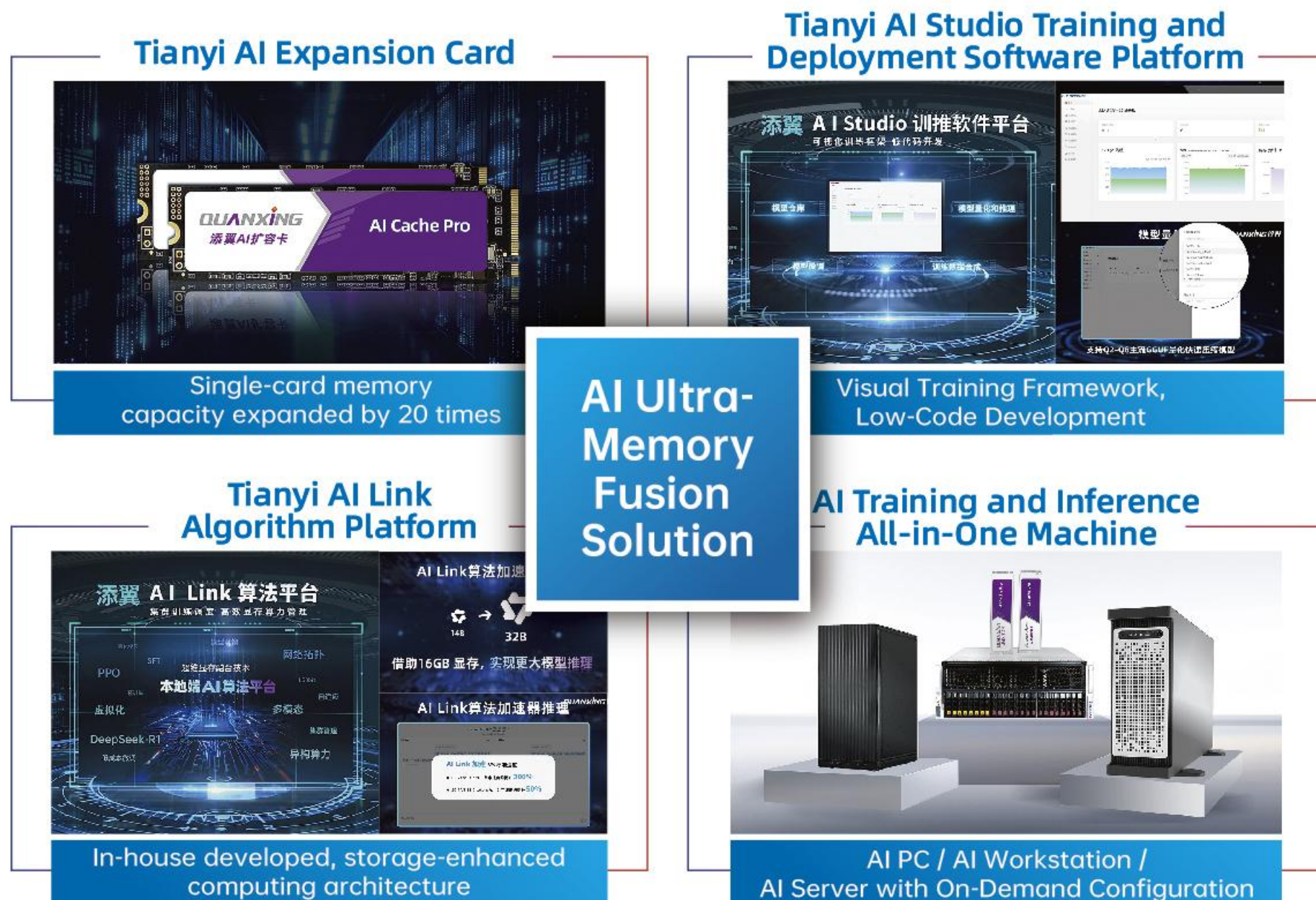
- Low Cost
- Low Power Consumption
- High Efficiency
- Empowering All Industries
- Enabling Localized Deployment of Large AI Models



AI

Leveraging years of expertise in storage technology, Quanxing Technology has pioneered an AI-powered ultra-memory fusion solution through its "**Hyper-Dimensional Memory Fusion Technology**" overcoming storage-computing bottlenecks.

Through its proprietary **Tianyi AI Expansion Card**, it extends single-card memory capacity by 20 times, unlocking unprecedented possibilities for local deployment of trillion-parameter large models. Combined with its unique **AI Link algorithm platform** and **AI Studio training-inference software platform**, it achieves a 90% reduction in training-inference costs and a 50% boost in inference concurrency performance. This empowers diverse industries to implement local AI applications cost-effectively, with low energy consumption and high efficiency.



Innovative R&D of Hyper-Dimensional Memory Fusion Technology

Innovative development of hyper-dimensional memory fusion technology and the Tianyi AI Expansion Card, expanding single-card memory capacity by 20 times. Supports local deployment and fine-tuning of large models with hundreds of billions of parameters, overcoming traditional storage-computing bottlenecks.

-  Hyper-dimensional Memory Fusion Technology
-  Strengthening Computing Through Memory
-  GPU Expansion
-  Intermediate Layer Driver Optimisation

Localised Deployment Cuts Training and Inference Costs by 90%

Through collaborative hardware-software innovation and intelligent scheduling optimisation via our proprietary AI Link algorithm platform, we achieve not only a 90% reduction in local training and inference deployment costs but also a 50% boost in model inference concurrency performance, delivering high performance at low cost.

-  Model Distillation
-  Inference Acceleration
-  Computational Heterogeneity
-  Training Cost Reduction





Lightweight Architecture Unleashes AI Application Potential

Our proprietary AI Studio training and inference software platform offers a visual training framework and low-code development, enabling users to assemble AI applications with the simplicity of building blocks and making model fine-tuning more straightforward.



Model Repository



Model Fine-Tuning



Model Quantisation
and Inference



Training Data Synthesis

Flexible Configuration for Efficient Deployment

Tailored configurations for AI PCs, AI workstations, and AI servers address diverse training and inference requirements. Achieve out-of-the-box functionality with one-click deployment, enabling SMEs without specialised technical teams to rapidly integrate bespoke AI capabilities.



Data Security



Out-of-the-box



One-Click Deployment



Supports Pure
Domestic Solutions

AI PC Inference Engine

R1 P14

R1 P14-T



AI PC Inference Engine	R1 P14 Compatible with the R1-14B model, it underpins basic operation and maintenance with a "three-year hardware after-sales service", cost-effectively meets the demands of small-model inference deployment, and serves as an "entry-level computing power box" for lightweight AI applications.	R1 P14-T Fully domestically-developed chip architecture addresses the core demand for compliance in the IT application innovation (Xinchuang) environment; with three-year hardware after-sales service providing a safety net, it makes the deployment of "Xinchuang + AI" more hassle-free, serving as a "compliant terminal" for lightweight inference in Xinchuang scenarios.
Parameter Item	Numerical value	
Number of Nodes	1	1
CPU	Intel i5-14500	Haiguang 3350
GPU	RTX5060 TI 16GB	Zhikai 50 16GB
Expansion Card	\	\
DRAM	32GB DDR5	32GB DDR5
System Disk	2TB	2TB
Data Disk	\	\
RAID Card	\	\
Network Card	Gigabit Network Card	Gigabit Network Card
MaximumModel for Inference	R1-14B	R1-14B
Maximum Model for Training	\	\
Inference Performance	1 concurrency, 15 TPS	\

Super AI PC
Training and Inference All-in-One Machine

Super R1 P14



Super AI PC
Training and
Inference
All-in-One Machine

Super R1 P14

It supports the "training → inference" closed-loop, with AI Cache boosting training efficiency. Hardware and software after-sales services simplify operation and maintenance, significantly lowering the barrier to "building AI models with zero prior experience" – making it an "all-in-one toolbox" for AI development in small teams.

Parameter Item	Numerical value
Number of Nodes	1
CPU	Intel i5-14500
GPU	RTX5060 TI 16GB
Expansion Card	AI Cache Lite
DRAM	128GB DDR5
System Disk	2TB
Data Disk	\
RAID Card	\
Network Card	Gigabit Network Card
MaximumModel for Inference	R1-14B
Maximum Model for Training	R1-14B, Qianwen-14B
Inference Performance	1 concurrency, 15 TPS

AI Workstation Inference Machine

R1 W70 Ultra



AI Workstation
Inference
Machine

R1 W70 Ultra

Multi-GPU + acceleration modules boost training / inference efficiency; Raid1 ensures data integrity. End-to-end after-sales support for long-cycle development resolves slow model iteration and data insecurity – serving as a "productivity hub" for professional-grade model development.

Parameter Item	Numerical value
Number of Nodes	1
CPU	Intel w5-3425
GPU	RTX5880 ada 48GB x 4
Expansion Card	\
DRAM	128GB DDR5
System Disk	960GB
Data Disk	7.68TB
RAID Card	\
Network Card	Gigabit Network Card
MaximumModel for Inference	R1-70B, R1-671B 1.58bit, Qianwen-72B
Maximum Model for Training	\
Inference Performance	30 concurrency, 923 TPS

Super AI Workstation
Training and Inference All-in-One Machine
Super R1 W70 Ultra



Super AI Workstation
Training and Inference
All-in-One Machine

Super R1 W70 Ultra

Multi-GPU + acceleration modules boost training / inference efficiency; Raid1 ensures data integrity. End-to-end after-sales support for long-cycle development resolves slow model iteration and data insecurity – serving as a "productivity hub" for professional-grade model development.

Parameter Item	Numerical value
Number of Nodes	1
CPU	Intel w5-3425
GPU	RTX5880 ada 48GB x 4
Expansion Card	AI Cache Pro x 2
DRAM	512GB DDR5
System Disk	960GB
Data Disk	7.68TB
RAID Card	\
Network Card	Gigabit Network Card
MaximumModel for Inference	R1-70B, R1-671B 1.58bit, Qianwen-72B
Maximum Model for Training	R1-70B, Qianwen-72B
Inference Performance	30 concurrency, 923 TPS

AI Server Inference Engine

R1 S671 Pro

R1 S671 Premium

R1 S70-T



AI Server Inference Engine	R1 S671 Pro 2-node cluster with 10-gigabit interconnection breaks through the computing power boundaries of "distributed training and inference"; with comprehensive after-sales coverage for top-level research risks, it stands as a "computing power carrier" for cutting-edge AI innovation.	R1 S671 Premium Equipped with "large-memory GPU + 1TB memory," it breaks through performance ceilings, transforming "ultra-large-scale model inference" from theoretical feasibility to engineering practicality. With full-cycle after-sales service providing a safety net, it serves as a "flagship solution" for extreme performance requirements.	R1 S70-T A domestically-developed multi-GPU cluster with 10-gigabit network cards enables "high-performance large-model inference" in the IT application innovation (Xinchuang) environment. Featuring both hardware and software after-sales services, it addresses the dual pain points of "compliance + computing power," serving as a "compliant computing power station" for large-model inference in Xinchuang scenarios.
----------------------------	--	--	---

Parameter Item	Numerical value		Numerical value
Number of Nodes	2		1
CPU	Intel 4410y x 2		Intel 8480 x 2
GPU	RTX5880 ada 48GB x 8		H20 96GB x 8
Expansion Card	\		\
DRAM	512GB DDR5		1024GB DDR5
System Disk	960GB x 2		960GB
Data Disk	7.68TB x 2		7.68TB
RAID Card	RAID 1		\
Network Card	10 Gigabit Network Card		10 Gigabit Network Card
MaximumModel for Inference	R1-671B Full Performance Version		R1-70B, Qianwen-72B
Maximum Model for Training	\		\
Inference Performance	20 concurrency, 50 TPS		48 concurrency, 973 TPS

Super AI Server
Training and Inference All-in-One Machine

Super R1 S70 Ultra
Super R1 S671 Ultra



Super AI Server
Training and
Inference
All-in-One Machine

Super R1 S70 Ultra

A multi-card cluster with AI acceleration slashes the turnaround time for "hundred-billion parameter model training and inference" from months down to a predictable timeframe. With Raid1 and end-to-end after-sales support, "large-scale model rollout" is no longer a risky endeavor – **it stands as a critical breakthrough platform for enterprise-level large model deployment.**

Super R1 S671 Ultra

2-node cluster with high-capacity interconnection pushes the boundaries of computing power for "distributed training and inference." With 4×AI Cache accelerating trillion-parameter training, and comprehensive after-sales coverage for top-tier research risks, **it stands as the "computing power flagship" for cutting-edge AI innovation.**

Parameter Item	Numerical value	
Number of Nodes	1	2
CPU	Intel 4410y x 2	Intel 4410y x 2
GPU	RTX5880 ada 48GB x 8	RTX5880 ada 48GB x 8
Expansion Card	AI Cache Pro x 2	AI Cache Pro x 4
DRAM	512GB DDR5	2TB DDR5
System Disk	960GB x 2	960GB x 2
Data Disk	7.68TB x 2	7.68TB x 2
RAID Card	RAID 1	RAID 1
Network Card	Gigabit Network Card	Broadcom 400Gb Network Card
MaximumModel for Inference	R1-671B Full Performance Version	R1-671B Full Performance Version
Maximum Model for Training	R1-70B, Qianwen-72B	R1-671B Full Performance Version
Inference Performance	20 concurrency, 50 TPS	48 concurrency, 973 TPS



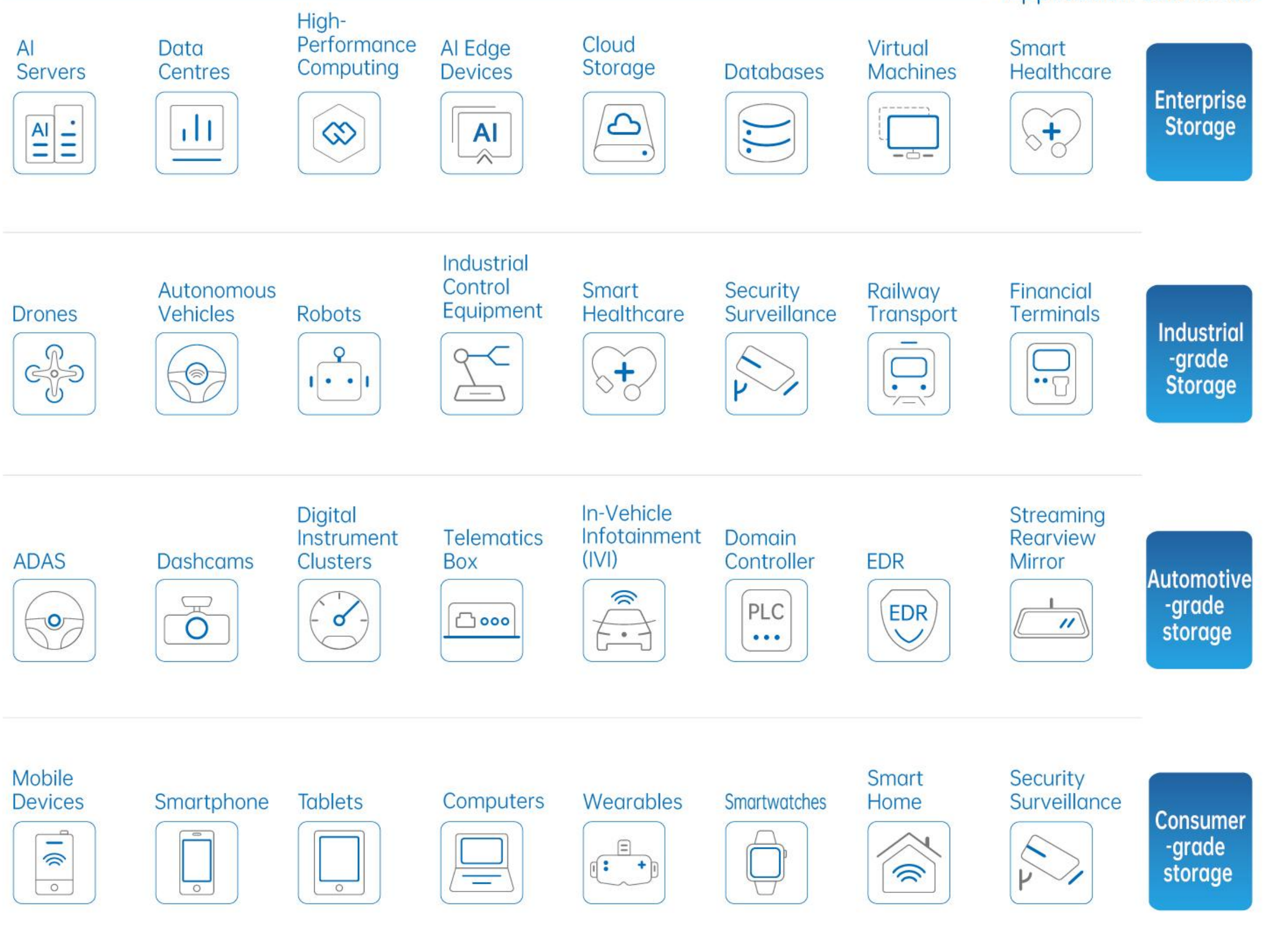
High-End Memory Chip Solutions

- Enterprise-grade Storage
- Industrial-grade Storage
- Automotive-grade Storage
- Consumer-grade Storage
- Industry-grade Storage



Quanxing Technology has established a comprehensive portfolio of **high-end storage products spanning enterprise-grade, industrial-grade, automotive-grade, and consumer-grade applications**. This enables the company to achieve high-standard mass production and import substitution for high-end storage products with full control over their development, **delivering all-scenario high-performance storage solutions for AI applications**.

Application Scenarios



Enterprise-Grade Storage Solutions

Designed for enterprise applications such as AI-driven high-performance computing, servers, and data centers, our storage solutions deliver high throughput, low latency, and exceptional performance efficiency. With core capabilities in scalable capacity, data security, and intelligent management, they provide stable support for high-value operations like large-scale data processing and real-time computing.

U.2 PCIe 5.0 QLC SSD
High-Performance Storage for the AI Era



■ Extreme Capacity

30.72TB~122.88TB
Massive storage scale supports
hundred-billion-parameter
model on-device

■ Outstanding Performance

PCIe 5.0 interface
14GB/s sequential read speed
Breaks data throughput bottlenecks

■ High Reliability

Dual-port design
Power Loss Protection
End-to-End Data Path Protection

■ Enhanced Security

Sanitize
SECDED
AES-XTS 256-bit Encryption
Metadata Protection

■ Energy Efficiency

4x higher capacity compared to
traditional HDDs
Optimized power, space, and
cooling efficiency
Reduces data center TCO

Model Name	ES04G01		ES04G02
Form Factor	U.2 15mm		
Interface	PCIe 5.0 x4 (single port x4 lanes / dual port x2 lanes)		
Flash	3D QLC		
Capacity	30.72TB	61.44TB	122.88TB
Sequential Read (MB/s)	14000	14000	14000
Sequential Write (MB/s)	2100	2100	2100
4KB IOPS	3000K	3000K	3000K
4KB IOPS	15.6K	15.6K	15.6K
Max Power	25W	30W	35W
Idle Power	20W	25W	25W
4K Random Read	110μs	110μs	110μs
4K Random Write	12μs	12μs	12μs
TBW (TB)	16800	33600	67200
DWPD	0.3		
UBER	< 1 sector per 10 ¹⁸ bits		
MTBF(Hours)	> 2.5 million hours		
Operating	0°C ~ 70°C		
Storage	-40°C ~ 85°C		
Operating Voltage	12V±10%		
Warranty	5 years		

U.2 PCIe 5.0 TLC SSD

Optimal Choice for AI Training/ High-Performance Computing



Model Name	ES14G01					ES34G01				
Form Factor	U.2 15mm					U.2 15mm				
Interface	PCIe 5.0 x4 (single port x4 lanes / dual port x2 lanes)					PCIe 5.0 x4 (single port x4 lanes / dual port x2 lanes)				
Flash	3D TLC					3D TLC				
Capacity	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB	1.6TB	3.2TB	6.4TB	12.8TB	25.6TB
Sequential Read (MB/s)	14000	14000	14000	14000	14000	14000	14000	14000	14000	14000
Sequential Write (MB/s)	4200	8500	8500	8400	7500	4200	8500	8500	8400	7500
4KB IOPS	2350K	3300K	3,000K	3,000K	3,000K	2400K	3000K	3000K	3000K	3000K
4KB IOPS	140K	320K	390K	420K	265K	390K	790K	880K	900K	615K
Max Power	25W	25W	25W	30W	35W	25W	25W	25W	30W	35W
Idle Power	5W	5W	5W	5W	5W	5W	5W	5W	5W	5W
4K Random Read	60μs	60μs	60μs	60μs	60μs	60μs	60μs	60μs	60μs	60μs
4K Random Write	10μs	10μs	10μs	10μs	10μs	10μs	10μs	10μs	10μs	10μs
TBW (TB)	3504	7008	14016	28032	56064	8760	17520	35040	70080	140160
DWPD	1					3				
UBER	< 1 sector per 10 ¹⁸ bits									
MTBF(Hours)	> 2.5 million hours									
Operating	0°C ~ 70°C									
Storage	-40°C ~ 85°C									
Operating Voltage	12V ± 10%									
Warranty	5 years									

U.3 PCIe 4.0 SSD DWPD=1

U.3 PCIe 4.0 SSD DWPD=3



Model Name	ES13H01					ES33H01				
Form Factor	U.3 / U.2 15mm					U.3 / U.2 15mm				
Interface	PCIe 4.0 ×4 (single port ×4 lanes / dual port ×2 lanes)					PCIe 4.0 ×4 (single port ×4 lanes / dual port ×2 lanes)				
Flash	3D TLC					3D TLC				
Capacity	1.92TB	3.84TB	7.68TB	15.36TB	30.72TB	1.6TB	3.2TB	6.4TB	12.8TB	25.6TB
Sequential Read (MB/s)	7000	7000	7000	7000	7000	7000	7000	7000	7000	7000
Sequential Write (MB/s)	3500	6700	6800	6800	6000	3500	6700	6800	6800	6000
4KB IOPS	1600K	1600K	1600K	1600K	1600K	1600K	1600K	1600K	1600K	1600K
4KB IOPS	95K	170K	180K	180K	180K	280K	430K	450K	480K	450K
Max Power	14W	19W	20W	21W	21W	14W	19W	20W	21W	21W
Idle Power	6W	6W	6W	8W	9W	6W	6W	6W	8W	9W
4K Random Read	110μs	100μs	100μs	100μs	90μs	110μs	100μs	100μs	100μs	90μs
4K Random Write	15μs	15μs	15μs	15μs	15μs	15μs	15μs	15μs	15μs	15μs
TBW (TB)	3504	7008	14016	28032	56064	8760	17520	35040	70080	140160
DWPD	1					3				
UBER	< 1 sector per 10 ¹⁸ bits									
MTBF(Hours)	2.5 million hours									
Operating	0°C ~ 70°C									
Storage	-40°C ~ 85°C									
Operating Voltage	12V ± 10%									
Warranty	5 years									

2.5" SATA SSD DWPD=1
 2.5" SATA SSD DWPD=3
 2.5" SATA SSD DWPD=0.5



Model Name	ES11A01					ES31A01				ES01A01			
Form Factor	2.5" 7mm					2.5" 7mm				2.5" 7mm			
Interface	SATA III					SATA III				SATA III			
Flash	3D TLC					3D TLC				3D TLC			
Capacity	480GB	960GB	1.92TB	3.84TB	7.68TB	480GB	960GB	1.92TB	3.84TB	1.92TB	3.84TB	7.68TB	15.36TB
Sequential Read (MB/s)	530	530	530	530	530	500	530	530	530	530	530	530	530
Sequential Write (MB/s)	430	500	500	500	500	440	500	500	500	500	500	500	500
4KB IOPS	96K	98K	98K	98K	97K	95K	98K	98K	98K	94K	97K	97K	94K
4KB IOPS	36K	42K	50K	37K	42K	40K	67K	77K	68K	13K	20K	14K	10K
Max Power	2.9W	3.2W	3.3W	3.4W	3.8W	2.9W	3.2W	3.3W	3.5W	3.3W	3.5W	3.5W	3.5W
Idle Power	1.3W	1.3W	1.4W	1.5W	1.6W	1.3W	1.4W	1.4W	1.6W	1.4W	1.6W	1.6W	1.6W
4K Random Read	115μs	115μs	115μs	120μs	145μs	130μs	125μs	130μs	125μs	130μs	125μs	125μs	125μs
4K Random Write	25μs	25μs	25μs	25μs	25μs	30μs	30μs	30μs	30μs	30μs	30μs	30μs	30μs
TBW (TB)	815	1714	3602	6507	14650	2447	4895	9790	19579	1720	3505	5950	10725
DWPD	1					3				0.5			
UBER	< 1 sector per 10 ¹⁷ bits												
MTBF(Hours)	> 2 million hours									> 1.5 million hours			
Operating	0°C ~ 70°C												
Storage	-40°C ~ 85°C												
Operating Voltage	5V ± 5%												
Warranty	5 years												

System Drive Series

M.2 2280 SATA III SSD DWPD=1

M.2 2280 PCIe 4.0 SSD DWPD=1



Model Name	ES11C01			ES13C01		
Form Factor	M.2 2280			M.2 2280		
Interface	SATA III			PCIe 4.0 ×4		
Flash	3D TLC			3D TLC		
Capacity	240GB	480GB	960GB	480GB	960GB	1.92TB
Sequential Read (MB/s)	530	530	530	6000	6000	6000
Sequential Write (MB/s)	290	480	500	700	1400	1800
4KB IOPS	60K	90K	98K	450K	750K	800K
4KB IOPS	10K	15K	30K	25K	50K	60K
Max Power	2.2W	2.7W	2.7W	7.9W	9.5W	9.8W
Idle Power	1.1W	1.1W	1.2W	3.5W	3.5W	3.5W
4K Random Read	120μs	120μs	120μs	75μs	75μs	75μs
4K Random Write	80μs	50μs	30μs	40μs	35μs	35μs
TBW (TB)	408	815	1631	850	1800	3700
DWPD	1					
UBER	< 1 sector per 10 ¹⁷ bits					
MTBF(Hours)	> 2 million hours					
Operating	0°C ~ 70°C					
Storage	-40°C ~ 85°C					
Operating Voltage	3.3V ± 5%					
Warranty	5 years					

Automotive-grade storage solutions

Specifically engineered for intelligent automotive systems, meeting the stringent demands of complex vehicle operating environments. Having passed the industry's most rigorous testing standards, it ensures stable operation under extreme temperatures, intense vibrations, and other challenging conditions. This provides reliable data storage assurance for intelligent driving and in-vehicle systems, making every journey safe and worry-free. Currently, Quanxing Technology has obtained automotive-grade IATF16949 quality system certification.

QUANXING MEM Automotive

eMMC

Series	MEM Series
Flash Type	2D MLC / 3D TLC
Capacity	4GB - 256GB
Sequential Read/Write(Max)	pSLC: R: 260MB/s W: 240MB/s TLC: R: 320MB/s W: 210MB/s
Operating Temperature	-40°C ~ 85°C / 105°C
Erase Cycles	pSLC≥30K / TLC≥3K
Package	BGA 153 Ball / BGA 100 Ball

QUANXING MUM Automotive

UFS

Series	MUM Series
Flash Type	3D TLC
Capacity	64GB - 512GB
Sequential Read/Write(Max)	R: 1550MB/s W: 1060MB/s
Operating Temperature	-40°C ~ 85°C / 105°C
Erase Cycles	≥3K
Package	BGA 153 Ball

QUANXING MPT Automotive

BGA SSD

Series	MPT Series
Flash Type	3D TLC
Capacity	64GB - 1TB
Sequential Read/Write(Max)	R: 3650MB/s W: 2900MB/s
Operating Temperature	-40°C ~ 85°C / 105°C
Erase Cycles	≥3K
Package	BGA 345 Ball / BGA 291 Ball

Micro SD / SD

Series	MIM Series
Flash Type	2D / 3D SLC, pSLC, MLC, TLC
Capacity	128GB - 2TB
Sequential Read/Write(Max)	R: 95MB/s W: 80MB/s
Operating Temperature	-40°C ~ 85°C
Erase Cycles	SLC≥60K / MLC≥3K
Package	SD / Micro SD



Industrial -grade storage solutions

Professional storage solutions for industrial applications such as drones, embodied robots, and autonomous vehicles, designed to meet the demands of high-intensity, continuous operation over extended periods. Their stable performance withstands harsh environments, providing enduring and reliable data storage support for the intelligent transformation and upgrading of diverse industrial scenarios.

U.2 PCIe 4.0 SSD



Model Name	ISC3G01 / ISB3G01				
Form Factor	U.2				
Interface	PCIe 4.0 ×4				
Flash	3D-TLC				
Capacity	480GB	960GB	1.92TB	3.84TB	7.68TB
Sequential Read (MB/s)	6500	7200	7150	7200	7200
Sequential Write (MB/s)	4000	6300	6400	6700	6300
4KB IOPS	430K	750K	1000K	920K	950K
4KB IOPS	950K	1000K	1200K	1200K	1000K
TBW (TB)	711	1588	3265	6429	13069
DWPD*	1.35	1.51	1.55	1.53	1.55
UBER	< 1 sector per 10 ¹⁶ bits				
MTBF(Hours)	> 2 million hours				
Operating	ISC3G01: -40~85℃ / ISB3G01: -20~70℃				
Warranty	3 years				

Super AI PC
Training and Inference All-in-One Machine

Super R1 P14



Super AI PC
Training and
Inference
All-in-One Machine

Super R1 P14

It supports the "training → inference" closed-loop, with AI Cache boosting training efficiency. Hardware and software after-sales services simplify operation and maintenance, significantly lowering the barrier to "building AI models with zero prior experience" – making it an "all-in-one toolbox" for AI development in small teams.

Parameter Item	Numerical value
Number of Nodes	1
CPU	Intel i5-14500
GPU	RTX5060 TI 16GB
Expansion Card	AI Cache Lite
DRAM	128GB DDR5
System Disk	2TB
Data Disk	\
RAID Card	\
Network Card	Gigabit Network Card
MaximumModel for Inference	R1-14B
Maximum Model for Training	R1-14B, Qianwen-14B
Inference Performance	1 concurrency, 15 TPS

M.2 2280 PCIe 4.0 SSD



Model Name	ISC3C01 / ISB3C01				
Form Factor	M.2 2280				
Interface	PCIe 4 x4				
Flash	3D-TLC				
Capacity	128GB	256GB	512GB	1TB	2TB
Sequential Read (MB/s)	1850	3800	4900	4900	3550
Sequential Write (MB/s)	850	1700	3200	3700	3150
4KB IOPS	110K	200K	450K	700K	600K
4KB IOPS	220K	400K	700K	800K	700K
TBW (TB)	86	248	661	1341	2876
DWPD*	0.62	0.88	1.18	1.2	1.28
UBER	< 1 sector per 10 ¹⁶ bits				
MTBF(Hours)	> 2 million hours				
Operating	ISC3C01 : -40~85℃ / ISB3C01 : -20~70℃				
Warranty	3 years				

M.2 2242 PCIe 4.0 SSD



Model Name	ISC3D01 / ISB3D01				
Form Factor	M.2 2242				
Interface	PCIe 4 x4				
Flash	3D-TLC				
Capacity	128GB	256GB	512GB	1TB	2TB
Sequential Read (MB/s)	1850	3800	4900	4900	3550
Sequential Write (MB/s)	850	1700	3200	3700	3150
4KB IOPS	110K	200K	450K	700K	600K
4KB IOPS	220K	400K	700K	800K	700K
TBW (TB)	86	248	661	1341	2876
DWPD*	0.62	0.88	1.18	1.2	1.28
UBER	< 1 sector per 10 ¹⁶ bits				
MTBF(Hours)	> 1.5 million hours				
Operating	ISC3D01 : -40~85℃ / ISB3D01 : -20~70℃				
Warranty	3 years				

M.2 2280 PCIe 3.0 SSD



Model Name	ISC2C01 / ISB2C01					
Form Factor	M.2 2280					
Interface	PCIe 3 x4					
Flash	3D-TLC					
Capacity	64GB	128GB	256GB	512GB	1TB	2TB
Sequential Read (MB/s)	1150	1150	2300	2400	2450	2450
Sequential Write (MB/s)	550	550	1100	1800	1900	1900
4KB IOPS	> 95K	> 95K	> 160K	> 230K	> 270K	> 270K
4KB IOPS	> 125K	> 125K	> 240K	> 400K	> 420K	> 420K
TBW (TB)	110	110	240	520	1120	2400
DWPD*	1.56	0.78	0.85	0.92	0.99	1.07
UBER	< 1 sector per 10 ¹⁶ bits					
MTBF(Hours)	> 2 million hours					
Operating	ISC2C01 : -40~85°C / ISB2C01 : -20~70°C					
Warranty	3 years					

M.2 2242 PCIe 3.0 SSD



Model Name	ISC2D01 / ISB2D01					
Form Factor	M.2 2280					
Interface	PCIe 3 x4					
Flash	3D-TLC					
Capacity	64GB	128GB	256GB	512GB	1TB	2TB
Sequential Read (MB/s)	1150	1150	2300	2400	2450	2450
Sequential Write (MB/s)	550	550	1100	1800	1900	1900
4KB IOPS	> 95K	> 95K	> 160K	> 230K	> 270K	> 270K
4KB IOPS	> 125K	> 125K	> 240K	> 400K	> 420K	> 420K
TBW (TB)	110	110	240	520	1120	2400
DWPD*	1.56	0.78	0.85	0.92	0.99	1.07
UBER	< 1 sector per 10 ¹⁶ bits					
MTBF(Hours)	> 2 million hours					
Operating	ISC2D01 : -40~85°C / ISB2D01 : -20~70°C					
Warranty	3 years					

2.5" SATA SSD



Model Name	ISC1A01 / ISB1A01					
Form Factor	2.5" SATA					
Interface	SATA III					
Flash	3D-TLC					
Capacity	64GB	128GB	256GB	512GB	1TB	2TB
Sequential Read (MB/s)	320	530	540	540	540	550
Sequential Write (MB/s)	260	450	485	500	500	510
4KB IOPS	> 24K	> 47.5K	> 72.5K	> 87K	> 94K	> 91.5K
4KB IOPS	> 56K	> 77.5K	> 82.5K	> 83.5K	> 84.5K	> 85K
TBW (TB)	70	100	250	600	1400	3300
DWPD*	0.99	0.71	0.89	1.07	1.24	1.47
UBER	< 1 sector per 10 ¹⁶ bits					
MTBF(Hours)	> 3 million hours					
Operating	ISC1A01 : -40~85°C / ISB1A01 : -20~70°C					
Warranty	3 years					

mSATA SSD



Model Name	ISC1B01 / ISB1B01					
Form Factor	mSATA					
Interface	SATA III					
Flash	3D-TLC					
Capacity	64GB	128GB	256GB	512GB	1TB	2TB
Sequential Read (MB/s)	320	530	540	540	540	550
Sequential Write (MB/s)	260	450	485	500	500	510
4KB IOPS	> 24K	> 47.5K	> 72.5K	> 87K	> 94K	> 91.5K
4KB IOPS	> 56K	> 77.5K	> 82.5K	> 83.5K	> 84.5K	> 85K
TBW (TB)	70	100	250	600	1400	3300
DWPD*	0.99	0.71	0.89	1.07	1.24	1.47
UBER	< 1 sector per 10 ¹⁶ bits					
MTBF(Hours)	> 3 million hours					
Operating	ISC2C01 : -40~85℃ / ISB2C01 : -20~70℃					
Warranty	3 years					

M.2 2280 SATA SSD



Model Name	ISC1C01 / ISB1C01					
Form Factor	M.2 2280					
Interface	SATA III					
Flash	3D-TLC					
Capacity	64GB	128GB	256GB	512GB	1TB	2TB
Sequential Read (MB/s)	320	530	540	540	540	550
Sequential Write (MB/s)	260	450	485	500	500	510
4KB IOPS	> 24K	> 47.5K	> 72.5K	> 87K	> 94K	> 91.5K
4KB IOPS	> 56K	> 77.5K	> 82.5K	> 83.5K	> 84.5K	> 85K
TBW (TB)	70	100	250	600	1400	3300
DWPD*	0.99	0.71	0.89	1.07	1.24	1.47
UBER	< 1 sector per 10 ¹⁶ bits					
MTBF(Hours)	> 3 million hours					
Operating	ISC1C01 : -40~85℃ / ISB1C01 : -20~70℃					
Warranty	3 years					

M.2 2242 SATA SSD



Model Name	ISC1D01 / ISB1D01					
Form Factor	M.2 2242					
Interface	SATA III					
Flash	3D-TLC					
Capacity	64GB	128GB	256GB	512GB	1TB	2TB
Sequential Read (MB/s)	320	530	540	540	540	550
Sequential Write (MB/s)	260	450	485	500	500	510
4KB IOPS	> 24K	> 47.5K	> 72.5K	> 87K	> 94K	> 91.5K
4KB IOPS	> 56K	> 77.5K	> 82.5K	> 83.5K	> 84.5K	> 85K
TBW (TB)	70	100	250	600	1400	3300
DWPD*	0.99	0.71	0.89	1.07	1.24	1.47
UBER	< 1 sector per 10 ¹⁶ bits					
MTBF(Hours)	> 3 million hours					
Operating	ISC1D01 : -40~85℃ / ISB1D01 : -20~70℃					
Warranty	3 years					

Embedded Storage Solutions

For embedded system applications such as industrial control, smart terminals, and automotive electronics, we provide storage chips and memory devices featuring miniaturization, high integration, wide temperature range adaptability, high-speed performance, low power consumption, reliability, and compatibility. These solutions ensure stable operation of embedded devices in complex environments.



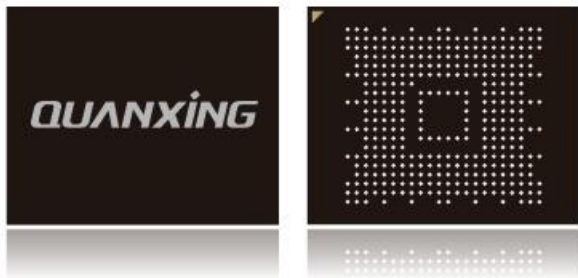
eMMC

Interface	eMMC 5.1 HS400	
Flash	pSLC / TLC	
Capacity	8GB - 256GB	
Dimensions & Specifications	FBGA153	11.5 × 13 mm
Operating Temperature	Consumer -grade : 0 °C ~ 70°C	Industrial -grade : -40°C ~ 85°C / 105°C



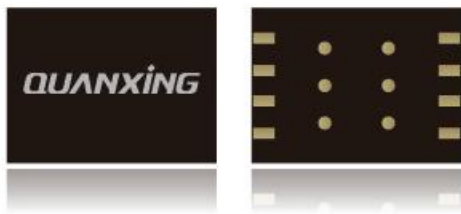
UFS

Interface	HS-G4x2 UFS 3.1	
Flash	3D TLC	
Capacity	64GB - 512GB	
Dimensions & Specifications	FBGA153	11.5 × 13 mm
Operating Temperature	Consumer -grade : 0 °C ~ 70°C	Industrial -grade : -40°C ~ 85°C / 105°C



BGA SSD

Interface	PCIe 4.0 ×4	
Flash	3D TLC	
Capacity	64GB - 1TB	
Dimensions & Specifications	BGA 291	16 × 20 mm
Operating Temperature	Consumer -grade : 0 °C ~ 70°C	Industrial -grade : -40°C ~ 85°C / 105°C



SPI NAND

接口	SPI 数据接口	
Flash 类型	SLC	
容量	128MB / 256MB / 512MB	
尺寸规格	LGA-8 6 × 8 mm	
工作温度	Consumer/Industrial-grade : 0 °C ~ 70°C	



SD NAND

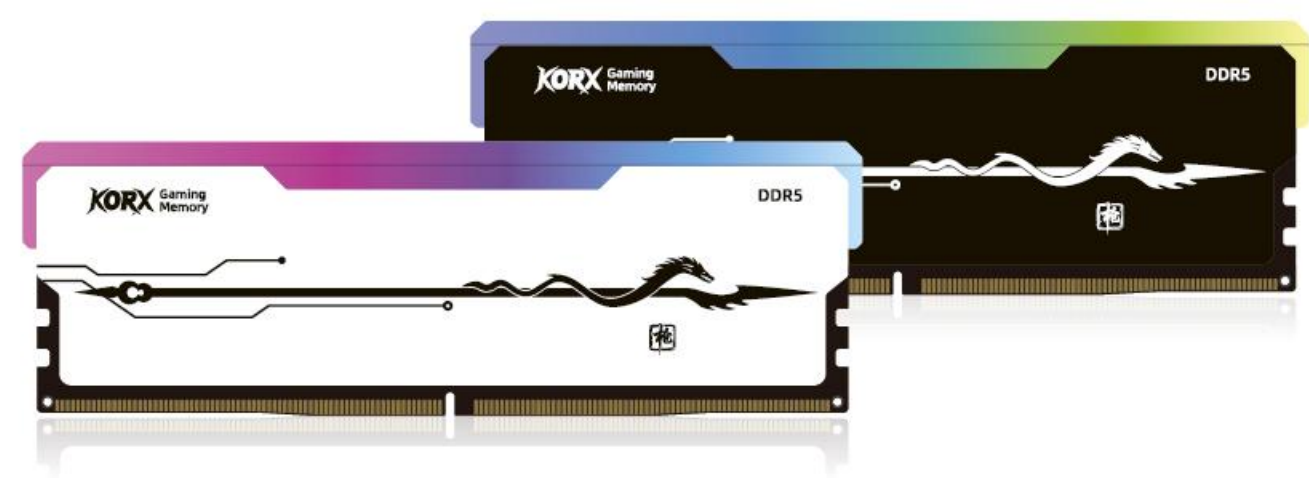
接口	SPI 数据接口 (SD 协议)	
Flash 类型	TLC	
容量	4GB / 8GB	
尺寸规格	LGA-8 6 × 8 mm	
工作温度	Consumer/Industrial-grade : -40°C ~ 85°C	

* 性能测试数据因平台差异可能有所不同

Consumer -Grade Storage Solutions

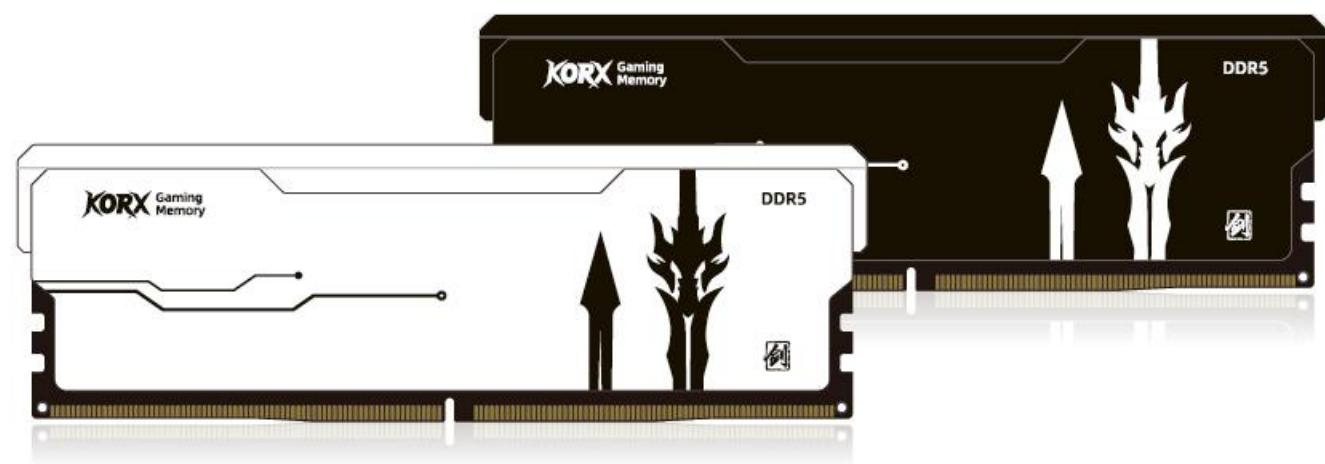
Intelligent storage solutions designed specifically for consumer electronics such as smart-phones, tablets, computers, and wearable devices. These solutions balance high-speed transfer rates with large-capacity requirements, perfectly suited for mobile office and multimedia entertainment scenarios. Featuring a simple, user-friendly design and excellent compatibility, they provide users with an on-demand, convenient experience while ensuring secure data storage. These solutions meet the diverse storage needs of individuals and families.

KORX- KNIGHT Series DDR5 RGB U-DIMM



Applicable Platforms	Desktop PC			
Module Specifications	288-pin DDR5 U-DIMM			
Frequency	6000 MHz	6400 MHz	6800 MHz	8000 MHz
Timing	CL=28	CL=32	CL=32	CL=36
Voltage (VDD)	1.4 V / 1.45V	1.35V	1.4 V / 1.45V	1.5V
Capacity	16GBx2 / 24GBx2 / 32GBx2	16GBx2 / 32GBx2 / 48GBx2	16GBx2 / 48GBx2	16GBx2 / 24GBx2

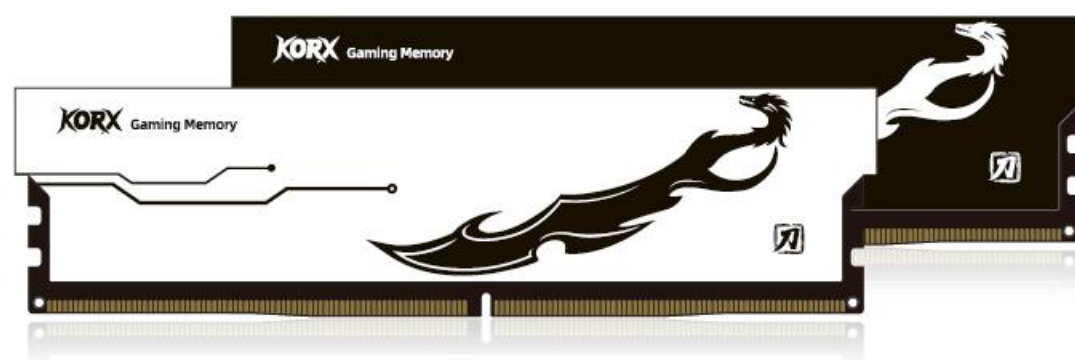
KORX- FENCER Series DDR5 U-DIMM



Applicable Platforms	Desktop PC		
Module Specifications	288-pin DDR5 U-DIMM		
Frequency	6000 MHz	6400 MHz	6800 MHz
Timing	CL=30 / 36 / 38 / 46	CL=32	CL=38
Voltage (VDD)	1.35V / 1.15V	1.4V	1.4V
Capacity	16GBx2 / 24GBx2 / 32GBx2	16GBx2 / 32GBx2 / 48GBx2	16GBx2

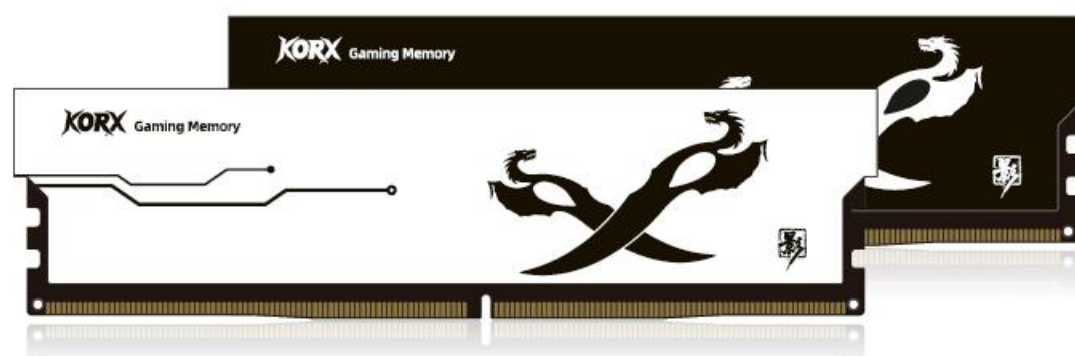


KORX- WARRIOR Series DDR4 U-DIMM



Applicable Platforms	Desktop PC	
Module Specifications	288-pin DDR4 U-DIMM	
Frequency	3200 MHz	3600 MHz
Timing	CL=18	CL=18
Voltage (VDD)	1.35V	1.35V
Capacity	8GBx2 / 16GBx2	8GBx2 / 16GBx2

KORX- ASSASSIN Series DDR4 U-DIMM



Applicable Platforms	Desktop PC	
Module Specifications	288-pin DDR4 U-DIMM	
Frequency	3200 MHz	3600 MHz
Timing	CL=22	CL=18
Voltage (VDD)	1.2V	1.35V
Capacity	8GB / 16GB	16GB

KORX- S Series DDR5 / DDR4 SO-DIMM



Applicable Platforms	Laptop		
Module Specifications	260-pin DDR5 SO-DIMM		260-pin DDR4 SO-DIMM
Frequency	5600 MHz	4800 MHz	3200 MHz
Timing	CL=46	CL=40	CL=22
Voltage (VDD)	1.1V	1.1V	1.2V
Capacity	16 / 32 GB	16 / 32 GB	8 / 16 / 32 GB



KORX- SSD QT01

Interface	SATA III				
Dimensions	100 × 70 × 7 mm				
Operating Temperature	0 °C ~ 70 °C				
Storage Temperature	- 40 °C ~ 85 °C				
Capacity	256G	512GB	1TB	2TB	4TB
Sequential Read Speed (max)	500MB/s	500MB/s	550MB/s	550MB/s	550MB/s
Sequential Write Speed (max)	400MB/s	400MB/s	450MB/s	450MB/s	450MB/s



KORX- SSD P400

Interface	PCIe 4.0 ×4			
Dimensions	80 × 22 × 2 mm			
Operating Temperature	0 °C ~ 70 °C			
Storage Temperature	- 40 °C ~ 85 °C			
Capacity	512GB	1TB	2TB	4TB
Sequential Read Speed (max)	7000MB/s	7400MB/s	7400MB/s	7400MB/s
Sequential Write Speed (max)	4200MB/s	6500MB/s	6500MB/s	6500MB/s



KORX- SSD P300

Interface	PCIe 3.0 ×4			
Dimensions	80 × 22 × 2 mm			
Operating Temperature	0 °C ~ 70 °C			
Storage Temperature	- 40 °C ~ 85 °C			
Capacity	256GB	512GB	1TB	2TB
Sequential Read Speed (max)	2800MB/s	2800MB/s	3500MB/s	3500MB/s
Sequential Write Speed (max)	1300MB/s	1300MB/s	2500MB/s	2500MB/s



QUANXING- 2.5 "SATA III SSD S101

Interface	SATA III 6Gb/s				
Dimensions	100 × 70 × 7 mm				
Operating Temperature	0 °C ~ 70 °C				
Storage Temperature	DC 5V +/-5%				
Capacity	128G	256G	512GB	1TB	2TB
Sequential Read Speed (max)	450MB/s	500MB/s	520MB/s	550MB/s	550MB/s
Sequential Write Speed (max)	400MB/s	450MB/s	480MB/s	500MB/s	500MB/s



QUANXING- M.2 PCIe 4.0 SSD N700

Interface	M.2 NVMe PCIe 4.0 ×4		
Dimensions	80 × 22 × 2 mm		
Operating Temperature	0 °C ~ 70 °C		
Storage Temperature	- 40 °C ~ 85 °C		
Capacity	1TB	2TB	4TB
Sequential Read Speed (max)	7000MB/s		
Sequential Write Speed (max)	6000MB/s		



QUANXING- M.2 PCIe 3.0 SSD N200

Interface	M.2 NVMe PCIe 3.0 ×4				
Dimensions	80 × 22 × 2 mm				
Operating Temperature	0 °C ~ 70 °C				
Storage Temperature	- 40 °C ~ 85 °C				
Capacity	128G	256G	512GB	1TB	2TB
Sequential Read Speed (max)	1800MB/s	2500MB/s			
Sequential Write Speed (max)	600MB/s	1800MB/s			

Industry -Specific Storage Solutions

Storage solutions engineered for specific industries or domains, customizable to meet unique sector requirements. Leveraging modular design and proven manufacturing systems, we deliver high-performance, highly reliable, and highly secure storage products while maintaining stable supply chain assurance.

DDR5 U-DIMM



Applicable Platforms	Desktop PC		
Module Specifications	288-pin DDR5 U-DIMM		
Frequency	4800 MHz	5200 MHz	5600 MHz
Timing	CL=40	CL=42	CL=46
Voltage (VDD)	1.1 V		
Capacity	8 / 16 / 24 / 32 GB		

DDR4 U-DIMM



Applicable Platforms	Desktop PC	
Module Specifications	288-pin DDR4 U-DIMM	
Frequency	2666 MHz	3200 MHz
Timing	CL=19	CL=22
Voltage (VDD)	1.2 V	
Capacity	4 / 8 / 16 GB	8 / 16 / 32 GB

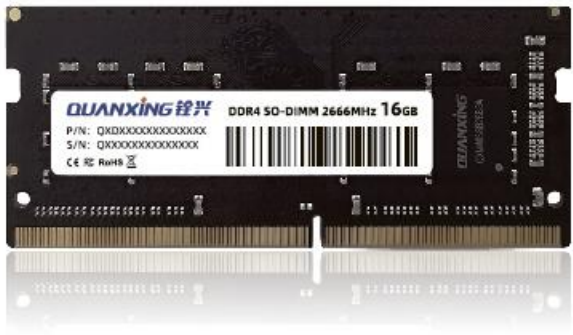


DDR5 SO-DIMM



Applicable Platforms	Laptop		
Module Specifications	262-pin DDR5 SO-DIMM		
Frequency	4800 MHz	5200 MHz	5600 MHz
Timing	CL=40	CL=42	CL=46
Voltage (VDD)	1.1 V		
Capacity	8 / 16 / 24 / 32 GB		

DDR4 SO-DIMM



Applicable Platforms	Laptop	
Module Specifications	260-pin DDR4 SO-DIMM	
Frequency	2666 MHz	3200 MHz
Timing	CL=19	CL=22
Voltage (VDD)	1.2 V	
Capacity	4 / 8 / 16 GB	8 / 16 / 32 GB

2.5 "SATA III SSD



Interface	SATA III 6Gb/s				
Dimensions	100 × 70 × 7 mm				
Operating Temperature	0 °C ~ 70 °C				
Storage Temperature	- 40 °C ~ 85 °C				
Capacity	128GB	256G	512GB	1TB	2TB
TBW (TB)	85	170	340	680	1360
MTBF	> 1.5 million hours				
Sequential Read Speed (max)	450MB/s	500MB/s	520MB/s	550MB/s	550MB/s
Sequential Write Speed (max)	400MB/s	450MB/s	480MB/s	500MB/s	500MB/s

mSATA SSD



Interface	SATA III 6Gb/s				
Dimensions	51 × 30 × 3.4 mm				
Operating Temperature	0 °C ~ 70 °C				
Storage Temperature	- 40 °C ~ 85 °C				
Capacity	128GB	256G	512GB	1TB	2TB
TBW (TB)	85	170	340	680	1360
MTBF	> 1.5 million hours				
Sequential Read Speed (max)	450MB/s	500MB/s	520MB/s	550MB/s	550MB/s
Sequential Write Speed (max)	400MB/s	450MB/s	480MB/s	500MB/s	500MB/s

M.2 2280 NGFF SSD



Interface	SATA III 6Gb/s				
Dimensions	80 × 22 × 2.1 mm				
Operating Temperature	0 °C ~ 70 °C				
Storage Temperature	- 40 °C ~ 85 °C				
Capacity	128GB	256G	512GB	1TB	2TB
TBW (TB)	85	170	340	680	1360
MTBF	> 1.5 million hours				
Sequential Read Speed (max)	450MB/s	500MB/s	520MB/s	550MB/s	550MB/s
Sequential Write Speed (max)	400MB/s	450MB/s	480MB/s	500MB/s	500MB/s

M.2 2230/2242 NVMe SSD M.2 2280 PCIe 4.0 SSD



Interface	PCIe 4.0 ×4			
Dimensions	30 / 42 / 80 × 22 × 2.2 mm			
Operating Temperature	0 °C ~ 70 °C			
Storage Temperature	- 40 °C ~ 85 °C			
Capacity	512GB	1TB	2TB	4TB
TBW (TB)	340	680	1360	2720
MTBF	> 1.5 million hours			
Sequential Read Speed (max)	4800~6300MB/s	5200~7000MB/s	5000~7200MB/s	7000MB/s
Sequential Write Speed (max)	3000~4000MB/s	4800~6000MB/s	4500~6000MB/s	6000MB/s

M.2 2230/2242 NVMe SSD M.2 2280 PCIe 3.0 SSD



Interface	PCIe 3.0 ×4			
Dimensions	30 / 42 / 80 × 22 × 2 mm			
Operating Temperature	0 °C ~ 70 °C			
Storage Temperature	- 40 °C ~ 85 °C			
Capacity	256GB	512GB	1TB	2TB
TBW (TB)	170	340	680	1360
MTBF	> 1.5 million hours			
Sequential Read Speed (max)	2500MB/s	3500MB/s	3500MB/s	3000MB/s
Sequential Write Speed (max)	1800MB/s	2500MB/s	3100MB/s	3100MB/s

4 Ecosystem Collaboration



Chuanxing Technology champions collaborative innovation across the industrial chain. By partnering with industry-academia-research institutions, channel partners, and core suppliers, we build an efficient AI and high-end storage chip ecosystem. Together, we drive technological innovation and market prosperity.

Industry -Academia -Research Collaboration

Through deep partnerships with universities, research institutes, and technical organizations, we accelerate the industrialization of cutting-edge technologies via joint R&D, talent development, and technology commercialization.

Agent Partnerships

Establish mutually beneficial partnerships with global agents, providing a comprehensive channel support system encompassing market strategies, brand empowerment, technical training, and more to jointly explore new industry opportunities.

Supplier Collaboration

Establish a robust supply chain synergy system with core suppliers. Through strategic partnerships, joint development, and collaborative quality initiatives, we jointly create more competitive solutions to serve global customers.

Contact Us

0755-83559311

support@quanxingtech.cn

Shenzhen Quanxing Technology Co., Ltd.

8th Floor, Vanke Binhai Cloud Centre, No. 3 Tai
Ran 8th Road, Futian District, Shenzhen

0755-83559311

www.quanxingtech.cn



Quanxing Wechat
Official Account



Quanxing
Official Website

Shenzhen Quantian Technology Co., Ltd.

5th-6th Floor, Building 1, Qixin Technology Park, 18
Jinxu Middle Road, Pingshan District, Shenzhen

0755-85208389

www.quantiantech.cn



Quantian Wechat
Official Account



Quantian
Official Website